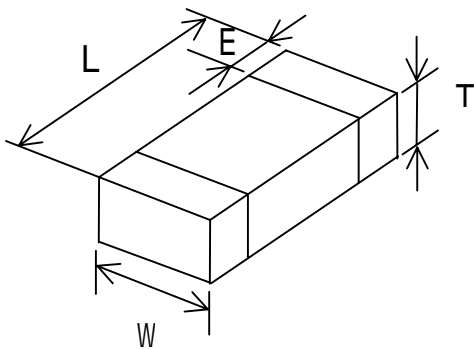


Multilayer chip bead 3216 (1206) series

PRODUCT DETAIL

Electrical Characteristics			Test Instruments
Z	Ω (Ref. Page 2)	TEST FREQ: 100 MHz	<ul style="list-style-type: none"> •HP4291B RF IMPEDANCE / MATERIAL ANALYZER •HP4338A/B MILLIOHMMETER •Agilent 8720ES S-PARAMETER NETWORK ANALYZER •HP6632B SYSTEM DC POWER SUPPLY
θ	NA		
SRF	NA		
DCR	Ω (Ref. Page 2)		
IDC	mA (Ref. Page 2)		

SHAPES AND DIMENSIONS



Unit : mm

TYPE	3216
L	3.2±0.20
W	1.6±0.20
T	1.1±0.20
E	0.5±0.30

Specification For Approval

Multilayer chip bead 3216 (1206) series

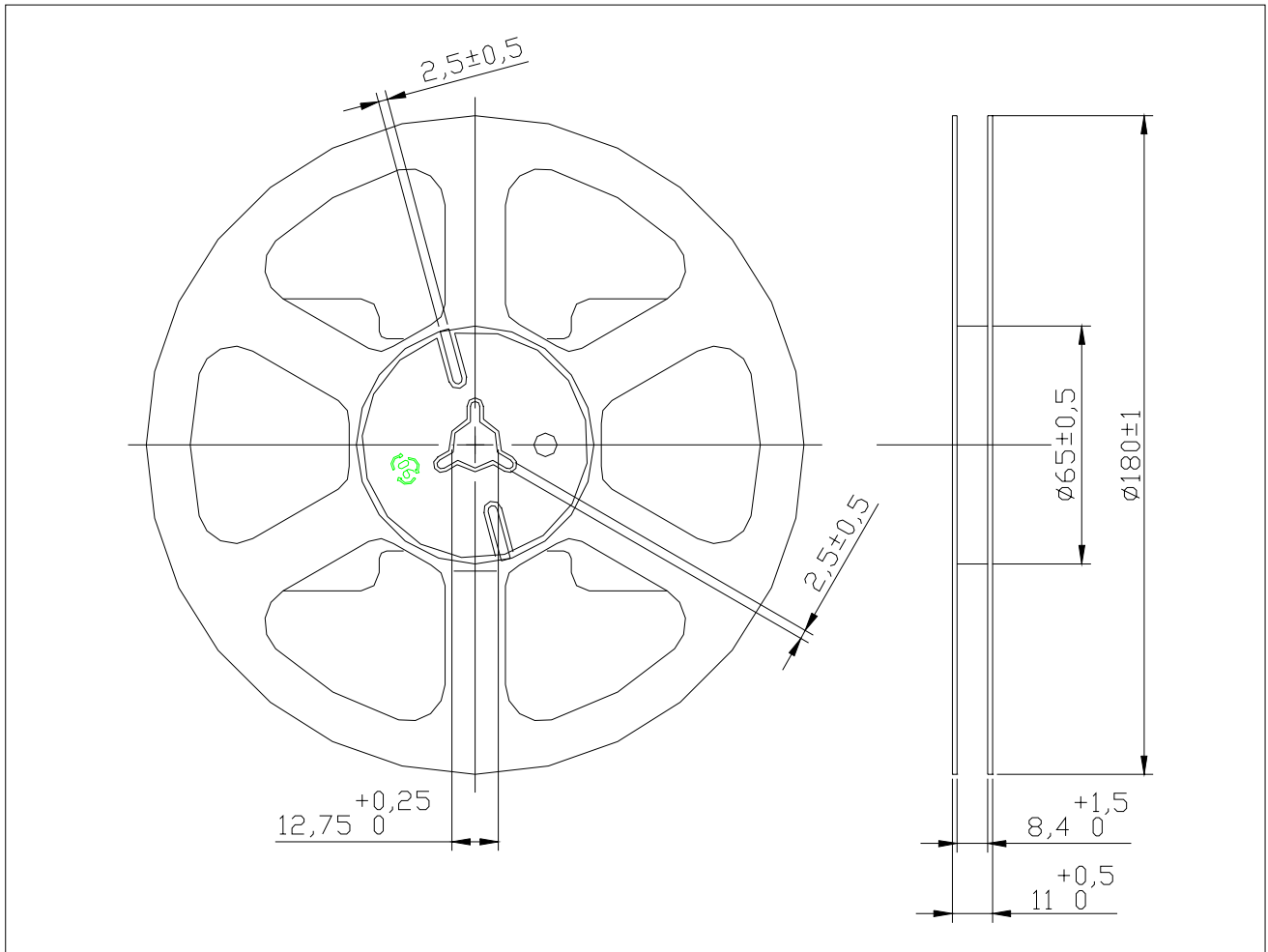
PART NUMBER AND CHARACTERISTICS TABLE BCCB-3216E1 SERIES

Part No.	Impedance(Ω) +/- 25%	Test Freq.(MHz)	DCR(Ω) (Max.)	Rated Current (mA)
BCCB-3216E1-190T	19	100	0.05	600
BCCB-3216E1-260T	26	100	0.05	600
BCCB-3216E1-310T	31	100	0.05	600
BCCB-3216E1-500T	50	100	0.08	600
BCCB-3216E1-600T	60	100	0.10	500
BCCB-3216E1-700T	70	100	0.10	600
BCCB-3216E1-900T	90	100	0.15	500
BCCB-3216E1-121T	120	100	0.15	500
BCCB-3216E1-151T	150	100	0.15	500
BCCB-3216E1-201T	200	100	0.20	500
BCCB-3216E1-221T	220	100	0.20	500
BCCB-3216E1-301T	300	100	0.20	500
BCCB-3216E1-601T	600	100	0.30	500
BCCB-3216E1-102T	1000	100	0.40	200
BCCB-3216E1-122T	1200	100	0.40	200
BCCB-3216E1-152T	1500	50	0.50	200
BCCB-3216E1-202T	2000	30	0.50	200

Specification For Approval

REEL DIMENSIONS

Unit: mm

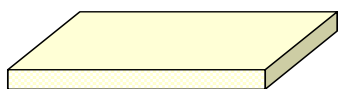
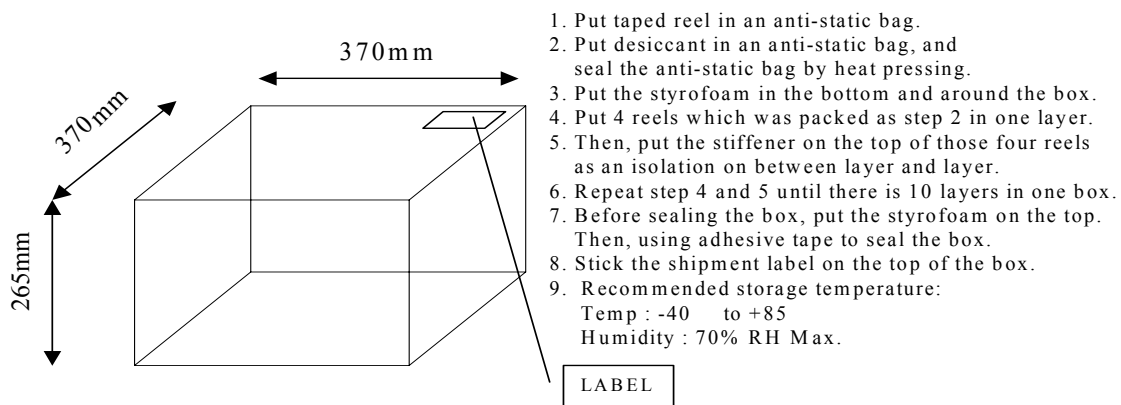


Reel Packaging Quantity									
PART SIZE		1005	1608	201209	201212	3216	3225	4516	4532
7" REEL	Qty. (pcs)	10,000	4,000	4,000	3,000	3,000	2,000	2,000	1,000
13" REEL		NA	NA	10,000	10,000	10,000	5,000	5,000	2,500
BULK		20,000	20,000	20,000	20,000	20,000	10,000	10,000	10,000

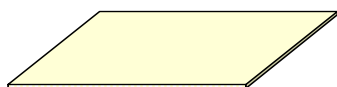
Specification For Approval

PACKING

Carton size	L*W*H (mm)	Loading Quantity 7" (reels)	Loading quantity 13" (reels)
L	370*370*265	40	12
M	370*370*133	20	5
S	370*200*133	20	-



Styrofoam: x 6 (350mm*350mm*15mm)



Stiffener: x 10 (340*340mm)



Taped reel + desiccant + anti-static bag: x 40

Specification For Approval

Leaching	The chip should not crack ; More than 90% of the terminal electrode should be covered with solder , free from defects, chip body should not exposed.	1.Solder: Alpha Sn100 2.Solder Temp: 260 ±5 3.Flux: Rosin 4.Dip time: 10 ±1 sec
Solderability 1 (IR Re-flow test)	1.Sn cover area need to over half thickness of chip 2.Chip shift distance under 50% of width 3.No short , open ,...etc defect symptom	1.Solder: M705-GRN360-K2-V Sn96.5/Ag3/Cu0.5 2.General:135/135/195/235 3.100% TIN:155/155/220/265
Solderability 2	More than 90% of the terminal electrode should be covered with new solder	1.Solder: Alpha Sn100 2.Solder Temp.:230 ±5 3.Flux: Rosin 4.Dip time: 4±1 sec
Terminal Strength	The terminal electrode should not break off nor the ferrite damaged	100505>0.2kgt , 160808>0.3kgt , 201209>0.6kgt , 201212>0.6kgt , 321611>1.0kgt , 322513>1.0kgt , 451616>1.0kgt , 453215>1.5kgt , BCCBA3216>1.2kgt ; pulling time:30 ±5 sec
Bending Strength	The ferrite should not be damaged by force applied on the right	100505>0.2kgf , 160808>0.3kgf , 201209>1.0kgf , 201212>1.0kgf , 321611>2.0kgf , 322513>2.5kgf , 451616>2.5kgf , 453215>2.5kgf , BCCBA3216>2.0kgf
Flexure Strength	No mechanical damage shall be noticed even when the board is bent 2 mm (0.079 inches)	1.At ambient temperature & Humidity 2.To bend 2 mm
Thermal Shock	1.No mechanical damage 2.Inductance should be within ±5% of the initial value 3.Q value should be within ±30% of the initial value 4.Impedance value should be	1.Temperature:-40 ~ 85 For 30 minutes each 2.Cycle: 100 cycles 3.Measurement: At ambient temperature 24 hours After test completion

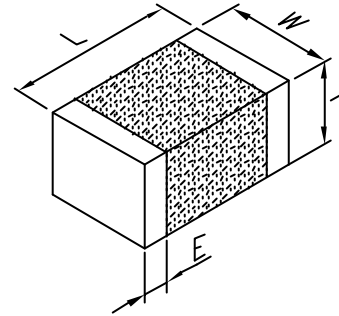
Specification For Approval

	within $\pm 20\%$ of the initial value	
Temperature Cycling	<ol style="list-style-type: none"> 1.No mechanical damage 2.Inductance should be within $\pm 5\%$ of the initial value 3.Q value should be within $\pm 30\%$ of the initial value 4.Impedance value should be within $\pm 20\%$ of the initial value 	<ol style="list-style-type: none"> 1. Temperature:-40~125 2. Cycle: 100 cycles 3. Measurement: At ambient temperature 24 hours After test completion
Biased Humidity	<ol style="list-style-type: none"> 1.No mechanical damage 2.Inductance should be within $\pm 5\%$ of the initial value 3.Q value should be within $\pm 30\%$ of the initial value 4.Impedance value should be within $\pm 20\%$ of the initial value 	<ol style="list-style-type: none"> 1.Temperature: 40 2.Humidity: 85 % RH 3.Applied current: Full rated current 4.Testing time: 1000 hrs 5. Measurement: At ambient temperature 24 hours After test completion
Rated Current	<ol style="list-style-type: none"> 1.BCCB / BCCL / BCCLH product Surface temperature below room temperature plus 10 2.High current DC power (ES) product surface temp. below room temperature plus 40 	<ol style="list-style-type: none"> 1.At ambient temperature & humidity 2.Testing time:5 minutes (under full rated current)

BCCB-3216E1-190T

ELECTRICAL CHARACTERISTICS:

	Z @ 100MHz (Ohms)	DCR (Ohms)	Rated Current
Nominal	19		
Minimum	14.25		
Maximum	23.75	0.05	600mA



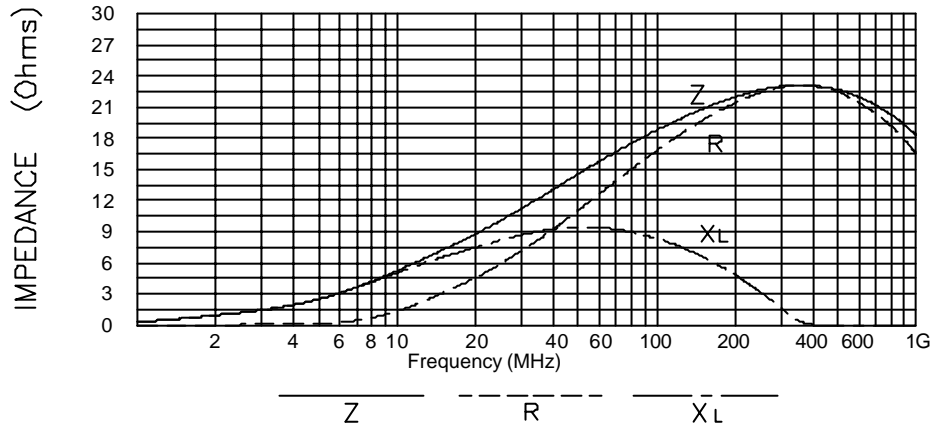
PHYSICAL DIMENSIONS:

- L 3.20(0.125) ±0.200(0.008)
- W 1.60(0.063) ±0.200(0.008)
- T 1.10(0.043) ±0.200(0.008)
- E 0.50(0.020) ±0.300(0.012)

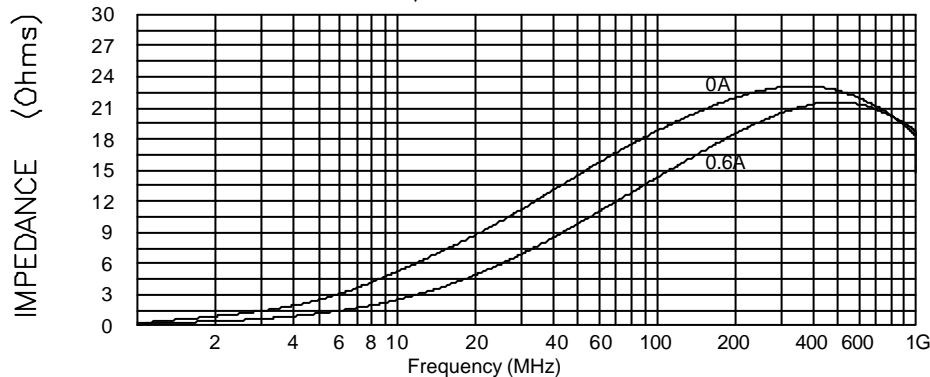
NOTES: UNLESS OTHERWISE SPECIFIED

- All edges and corners must be rounded.
- Dimensions are in millimeters (inches)
- Taped and Reeled per current EIA specification.

|Z| , R, AND X_L vs. FREQUENCY



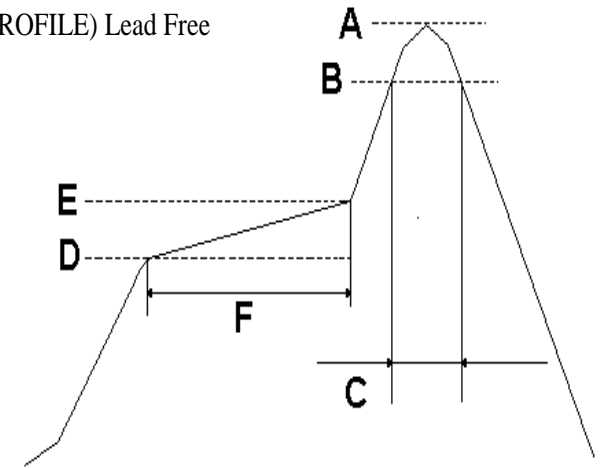
Z vs. FREQUENCY
Impedance Under DC Bias



Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

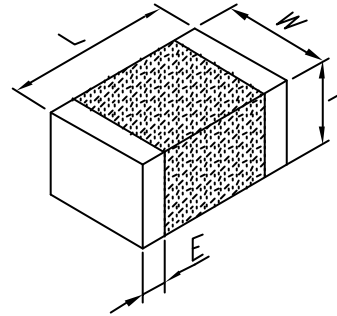
A	260 ± 5
B	230 ± 5
C	30 ± 10sec
D	150
E	180
F	90 ± 30sec



BCCB-3216E1-260T

ELECTRICAL CHARACTERISTICS:

	Z @ 100MHz (Ohms)	DCR (Ohms)	Rated Current
Nominal	26		
Minimum	19.5		
Maximum	32.5	0.05	600mA



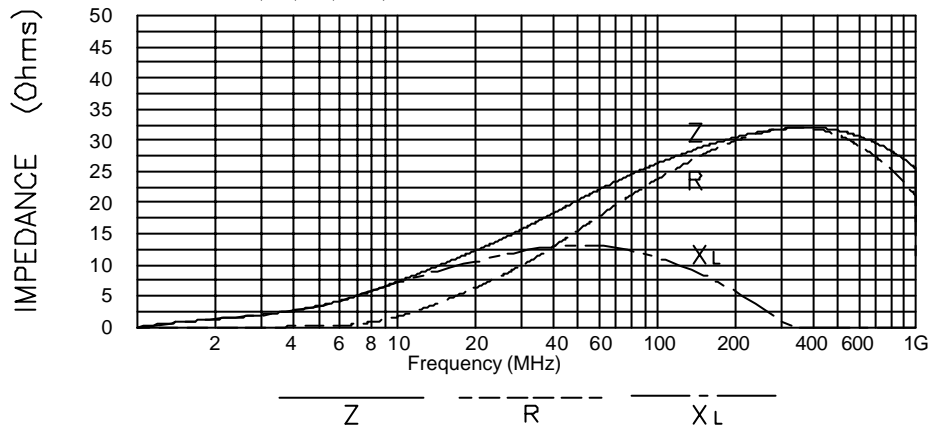
PHYSICAL DIMENSIONS:

L	3.20(0.126) ±0.200(0.008)
W	1.60(0.063) ±0.200(0.008)
T	1.10(0.043) ±0.200(0.008)
E	0.50(0.020) ±0.300(0.012)

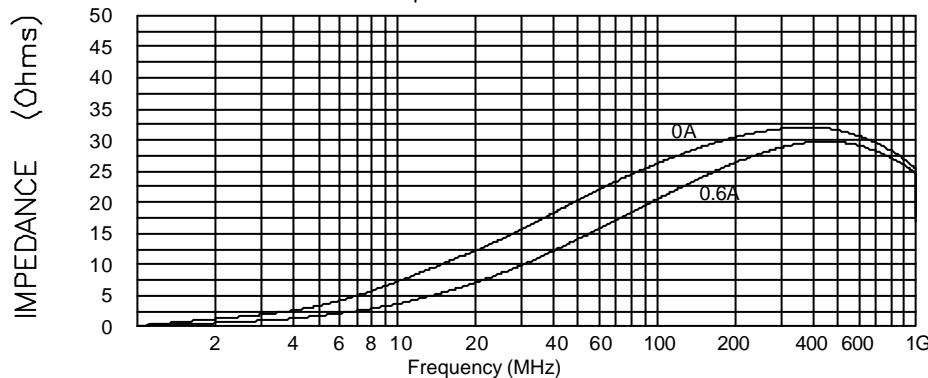
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

|Z| , R, AND X_L vs. FREQUENCY



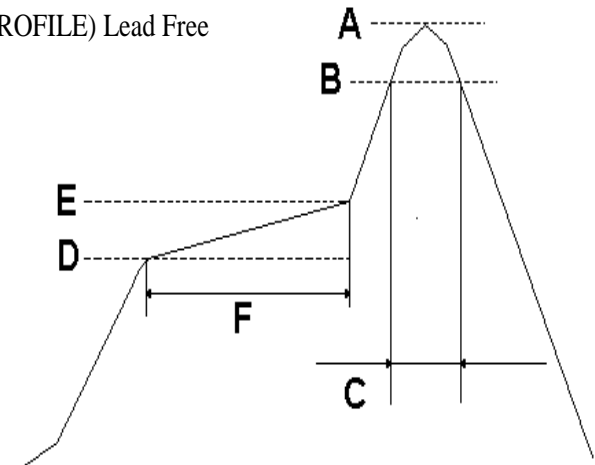
Z vs. FREQUENCY
Impedance Under DC Bias



Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

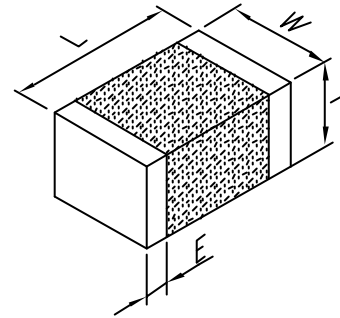
A	260 ± 5
B	230 ± 5
C	30 ± 10sec
D	150
E	180
F	90 ± 30sec



BCCB-3216E1-310T

ELECTRICAL CHARACTERISTICS:

	Z @ 100MHz (Ohms)	DCR (Ohms)	Rated Current
Nominal	31		
Minimum	23.25		
Maximum	38.75	0.05	600mA



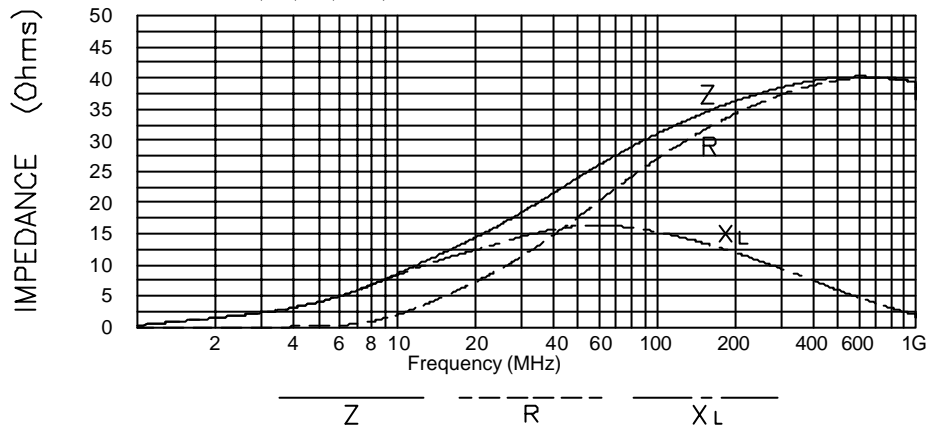
PHYSICAL DIMENSIONS:

L	3.20(0.126) ±0.200(0.008)
W	1.60(0.063) ±0.200(0.008)
T	1.10(0.043) ±0.200(0.008)
E	0.50(0.020) ±0.300(0.012)

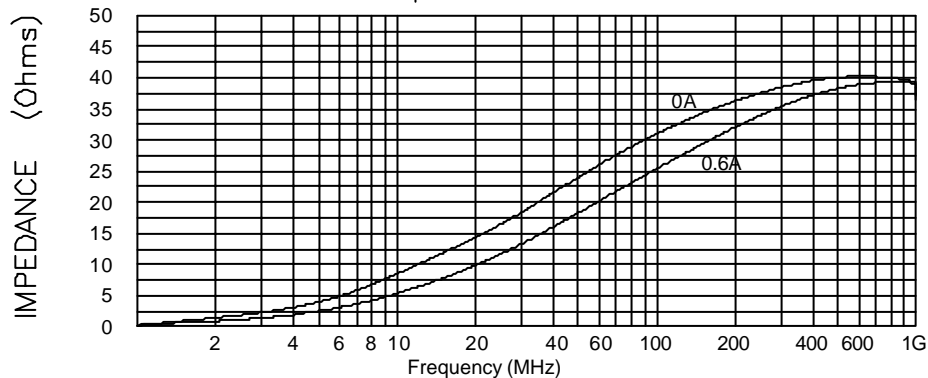
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

|Z| , R, AND X_L vs. FREQUENCY



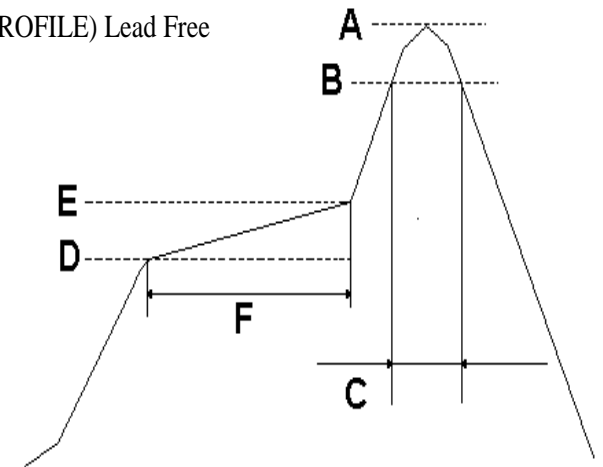
Z vs. FREQUENCY
Impedance Under DC Bias



Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

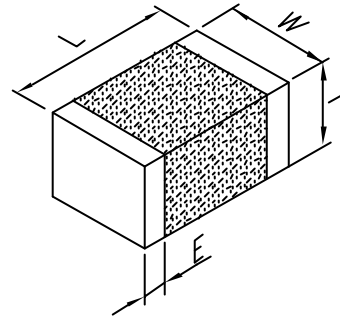
A	260 ± 5
B	230 ± 5
C	30 ± 10sec
D	150
E	180
F	90 ± 30sec



BCCB-3216E1-500T

ELECTRICAL CHARACTERISTICS:

	Z @ 100MHz (Ohms)	DCR (Ohms)	Rated Current
Nominal	50		
Minimum	37.5		
Maximum	62.5	0.08	600mA



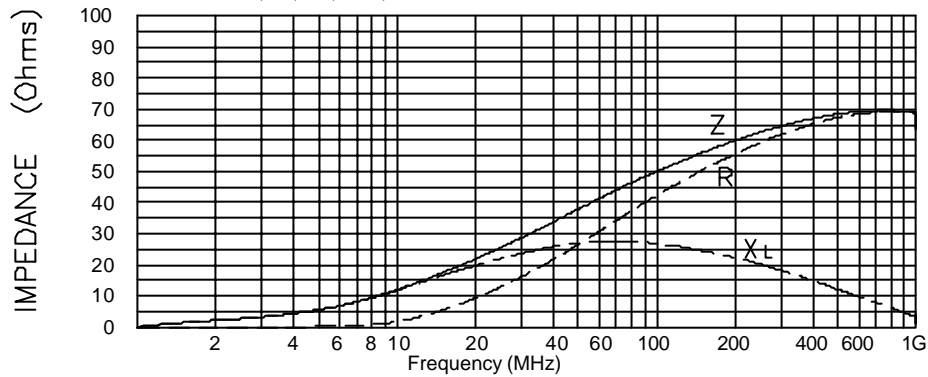
PHYSICAL DIMENSIONS:

L	3.20(0.126) ±0.200(0.008)
W	1.60(0.063) ±0.200(0.008)
T	1.10(0.043) ±0.200(0.008)
E	0.50(0.020) ±0.300(0.012)

NOTES: UNLESS OTHERWISE SPECIFIED

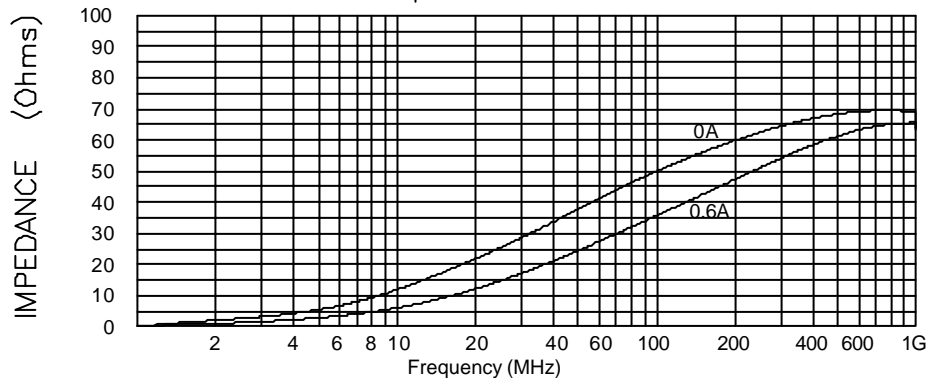
- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

|Z| , R, AND X_L vs. FREQUENCY



— Z — R — X_L

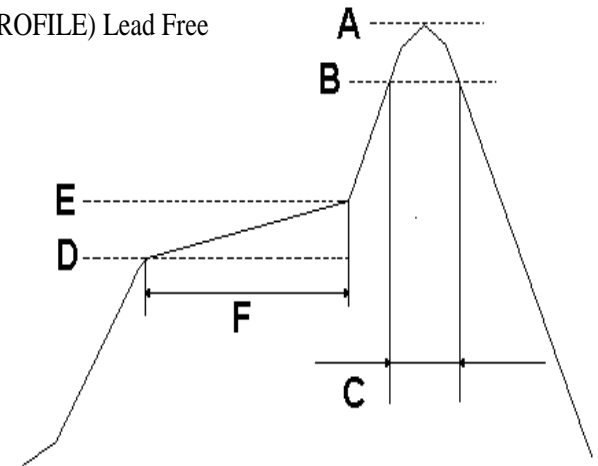
Z vs. FREQUENCY
Impedance Under DC Bias



Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

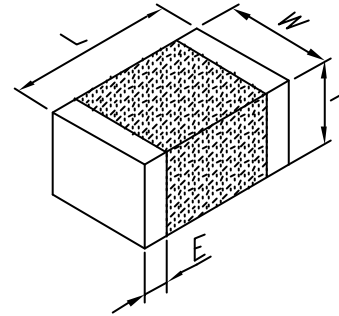
A	260 ± 5
B	230 ± 5
C	30 ± 10sec
D	150
E	180
F	90 ± 30sec



BCCB-3216E1-700T

ELECTRICAL CHARACTERISTICS:

	Z @ 100MHz (Ohms)	DCR (Ohms)	Rated Current
Nominal	70		
Minimum	52.5		
Maximum	87.5	0.1	600mA



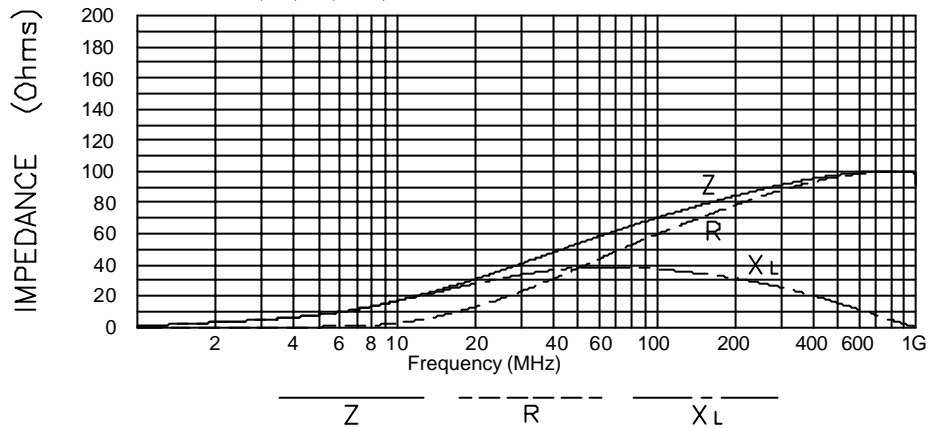
PHYSICAL DIMENSIONS:

L	3.20(0.125) ±0.200(0.008)
W	1.60(0.063) ±0.200(0.008)
T	1.10(0.043) ±0.200(0.008)
E	0.50(0.020) ±0.300(0.012)

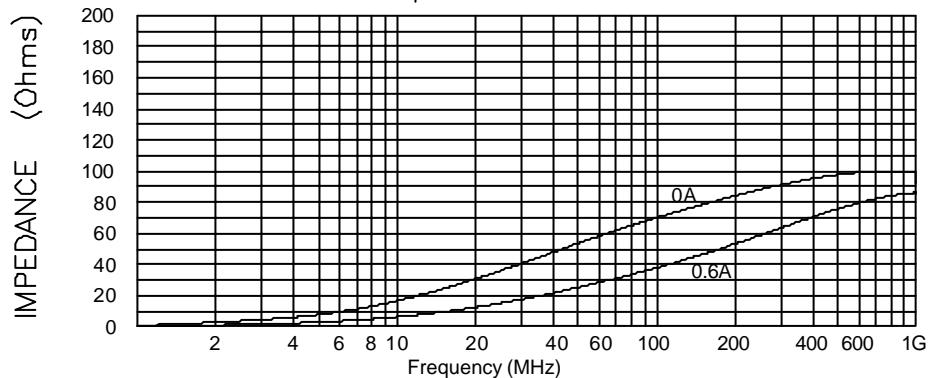
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

|Z| , R, AND X_L vs. FREQUENCY



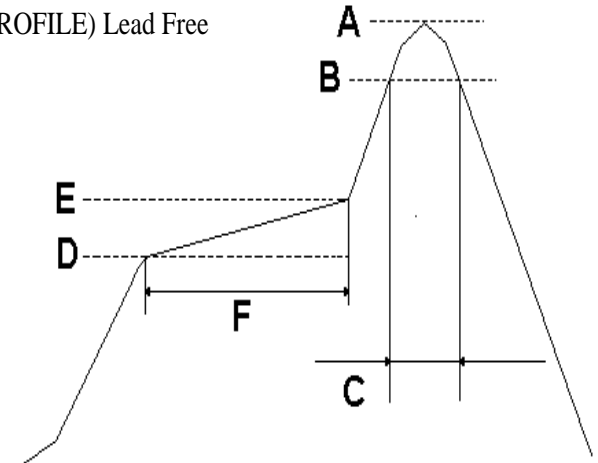
Z vs. FREQUENCY
Impedance Under DC Bias



Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

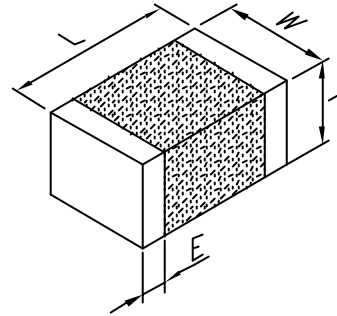
A	260 ± 5
B	230 ± 5
C	30 ± 10sec
D	150
E	180
F	90 ± 30sec



BCCB-3216E1- 900T

ELECTRICAL CHARACTERISTICS:

	Z @ 100MHz (Ohms)	DCR (Ohms)	Rated Current
Nominal	90		
Minimum	67.5		
Maximum	112.5	0.15	500mA



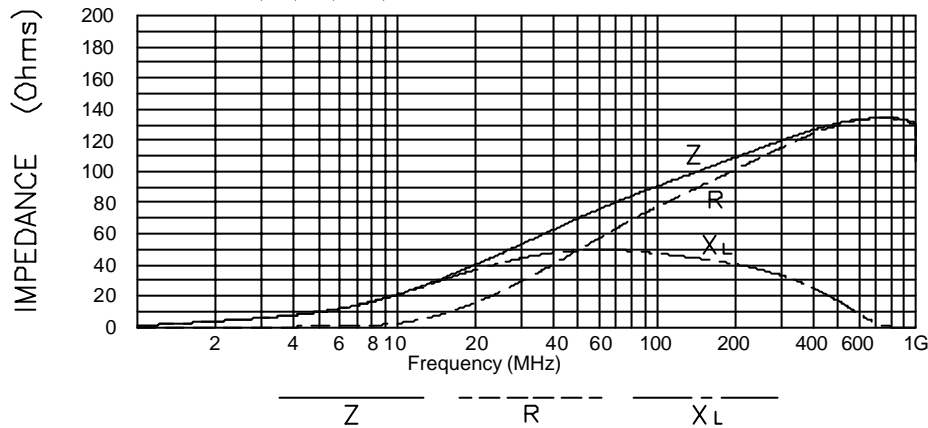
PHYSICAL DIMENSIONS:

L	3.20(0.126) ±0.200(0.008)
W	1.60(0.063) ±0.200(0.008)
T	1.10(0.043) ±0.200(0.008)
E	0.50(0.020) ±0.300(0.012)

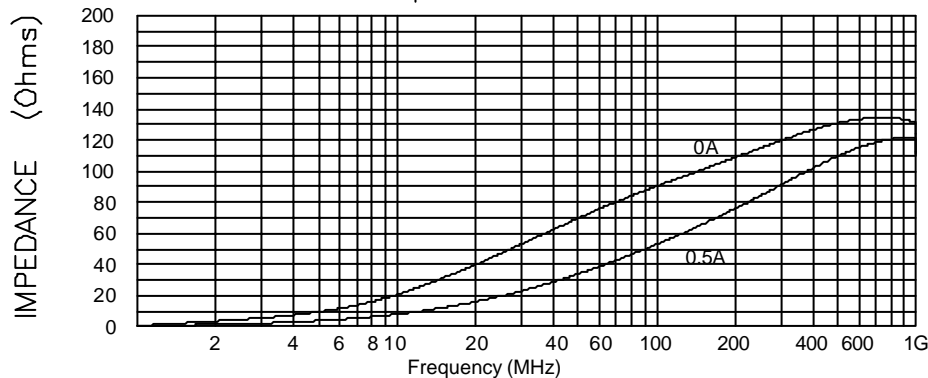
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

|Z| , R, AND X_L vs. FREQUENCY



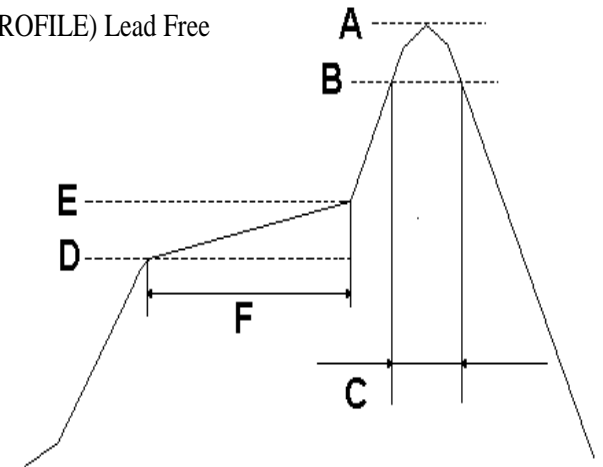
Z vs. FREQUENCY
Impedance Under DC Bias



Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

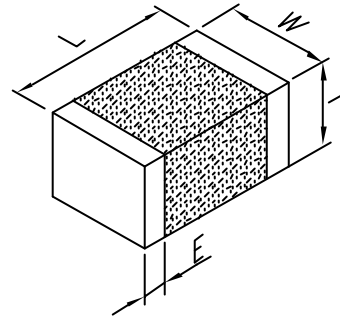
A	260 ± 5
B	230 ± 5
C	30 ± 10 sec
D	150
E	180
F	90 ± 30 sec



BCCB-3216E1-121T

ELECTRICAL CHARACTERISTICS:

	Z @ 100MHz (Ohms)	DCR (Ohms)	Rated Current
Nominal	120		
Minimum	90		
Maximum	150	0.15	500mA



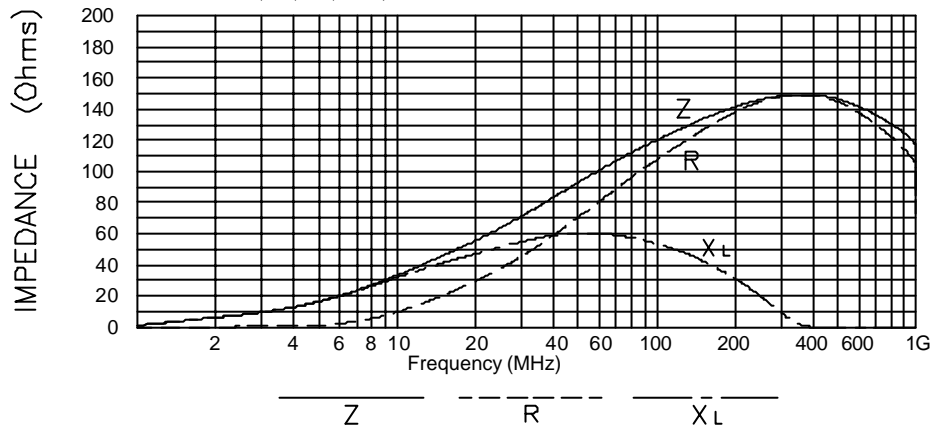
PHYSICAL DIMENSIONS:

- L 3.20(0.125) ±0.200(0.008)
- W 1.60(0.063) ±0.200(0.008)
- T 1.10(0.043) ±0.200(0.008)
- E 0.50(0.020) ±0.300(0.012)

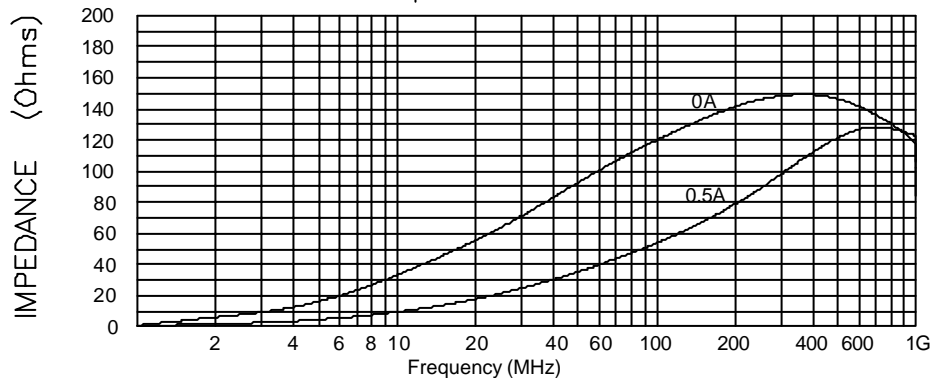
NOTES: UNLESS OTHERWISE SPECIFIED

- All edges and corners must be rounded.
- Dimensions are in millimeters (inches)
- Taped and Reeled per current EIA specification.

|Z| , R, AND X_L vs. FREQUENCY



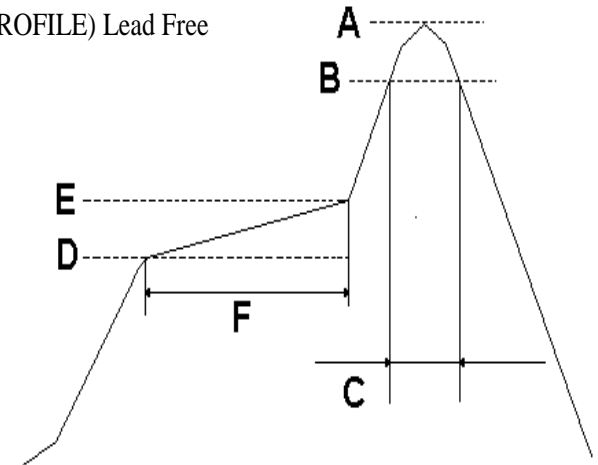
Z vs. FREQUENCY
Impedance Under DC Bias



Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

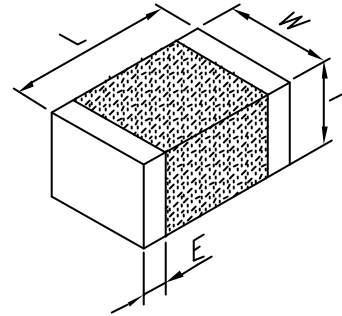
A	260 ± 5
B	230 ± 5
C	30 ± 10sec
D	150
E	180
F	90 ± 30sec



BCCB-3216E1-151T

ELECTRICAL CHARACTERISTICS:

	Z @ 100MHz (Ohms)	DCR (Ohms)	Rated Current
Nominal	150		
Minimum	112.5		
Maximum	187.5	0.15	500mA



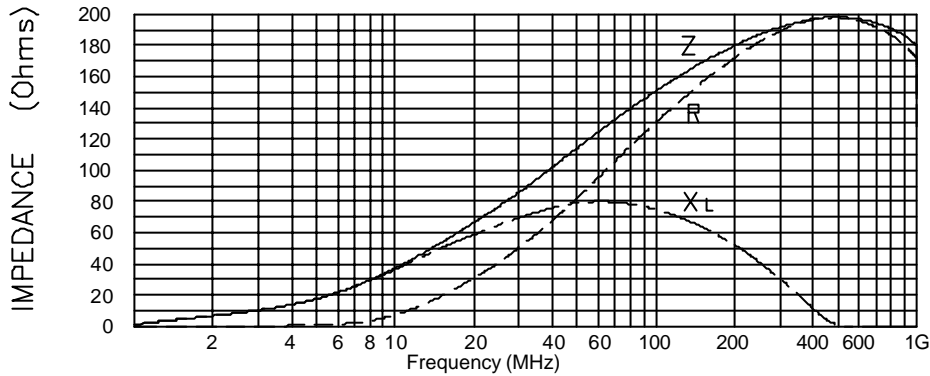
PHYSICAL DIMENSIONS:

L	3.20(0.126) ±0.200(0.008)
W	1.60(0.063) ±0.200(0.008)
T	1.10(0.043) ±0.200(0.008)
E	0.50(0.020) ±0.300(0.012)

NOTES: UNLESS OTHERWISE SPECIFIED

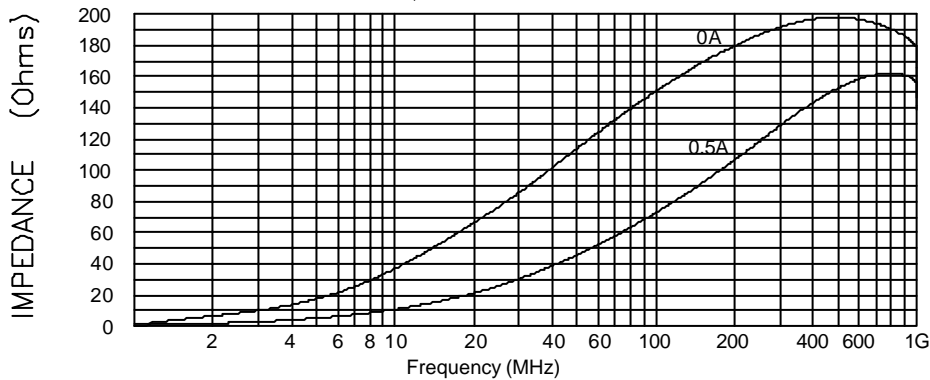
- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

|Z| , R, AND X_L vs. FREQUENCY



— Z — R — X_L

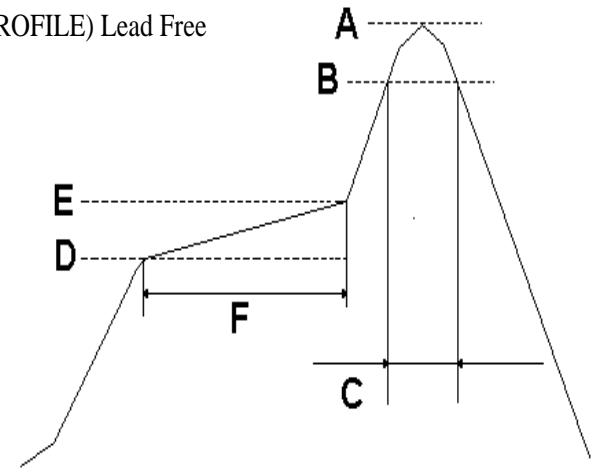
Z vs. FREQUENCY
Impedance Under DC Bias



Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

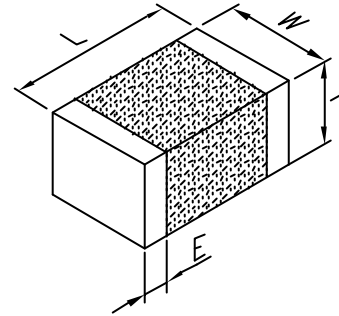
A	260 ± 5
B	230 ± 5
C	30 ± 10sec
D	150
E	180
F	90 ± 30sec



BCCB-3216E1-201T

ELECTRICAL CHARACTERISTICS:

	Z @ 100MHz (Ohms)	DCR (Ohms)	Rated Current
Nominal	200		
Minimum	150		
Maximum	250	0.2	500mA



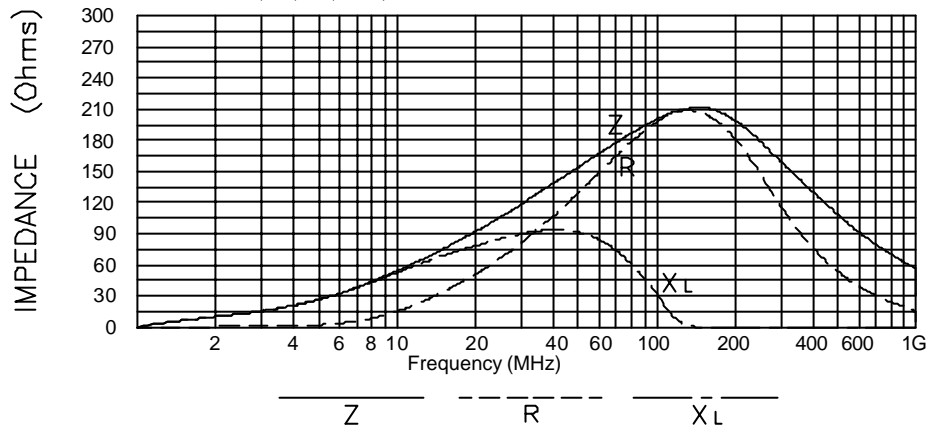
PHYSICAL DIMENSIONS:

L	3.20(0.126) ±0.200(0.008)
W	1.60(0.063) ±0.200(0.008)
T	1.10(0.043) ±0.200(0.008)
E	0.50(0.020) ±0.300(0.012)

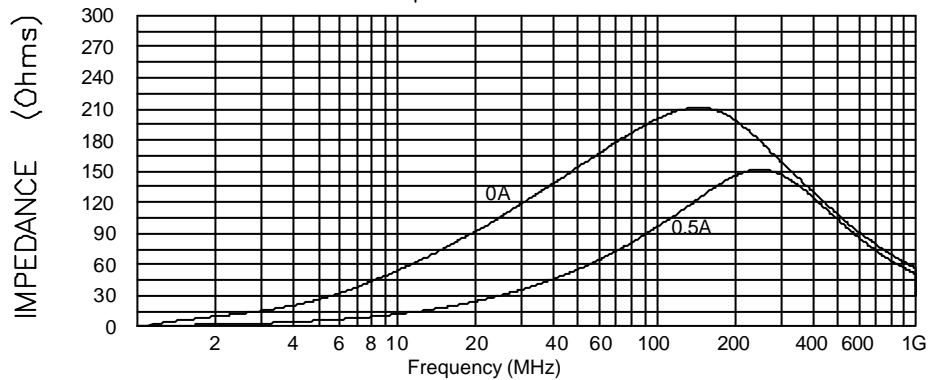
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

|Z| , R, AND X_L vs. FREQUENCY



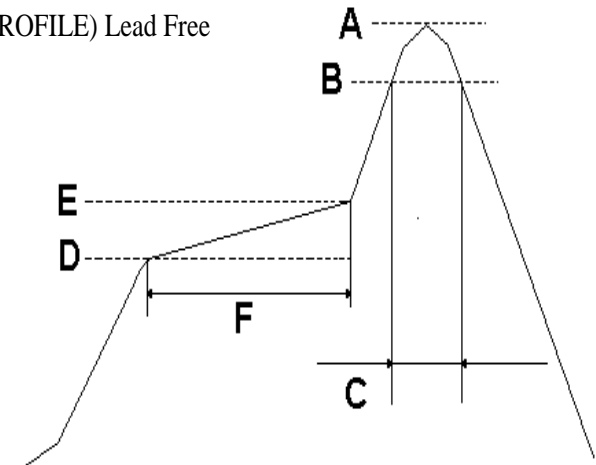
Z vs. FREQUENCY
Impedance Under DC Bias



Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

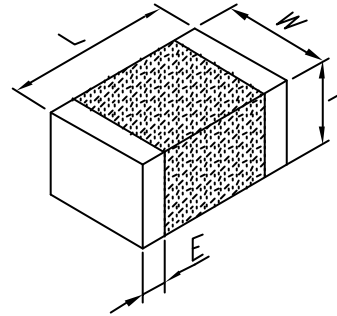
A	260 ± 5
B	230 ± 5
C	30 ± 10sec
D	150
E	180
F	90 ± 30sec



BCCB-3216E1-221T

ELECTRICAL CHARACTERISTICS:

	Z @ 100MHz (Ohms)	DCR (Ohms)	Rated Current
Nominal	220		
Minimum	165		
Maximum	275	0.2	500mA



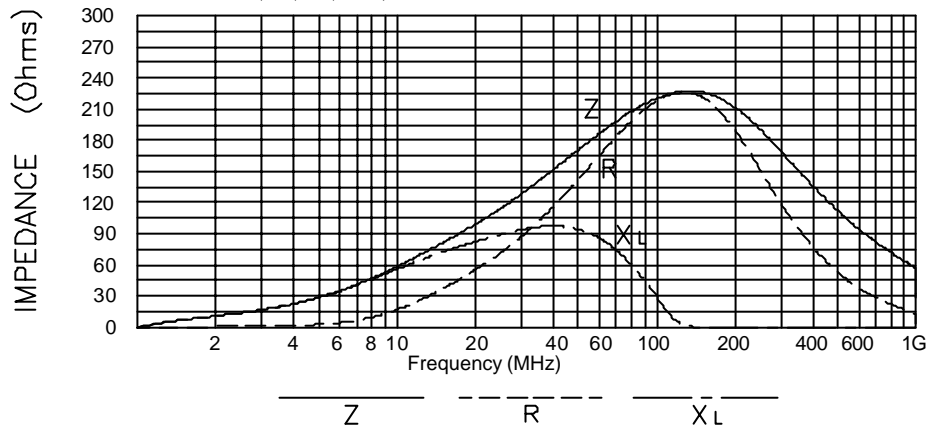
PHYSICAL DIMENSIONS:

L	3.20(0.126) ±0.200(0.008)
W	1.60(0.063) ±0.200(0.008)
T	1.10(0.043) ±0.200(0.008)
E	0.50(0.020) ±0.300(0.012)

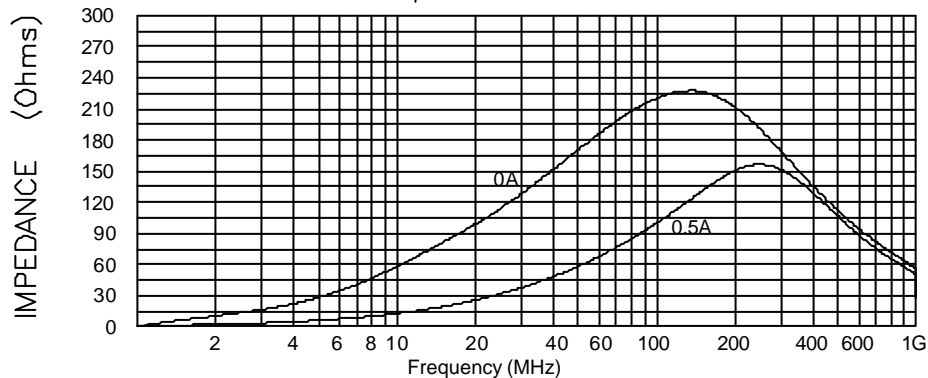
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

|Z| , R, AND X_L vs. FREQUENCY



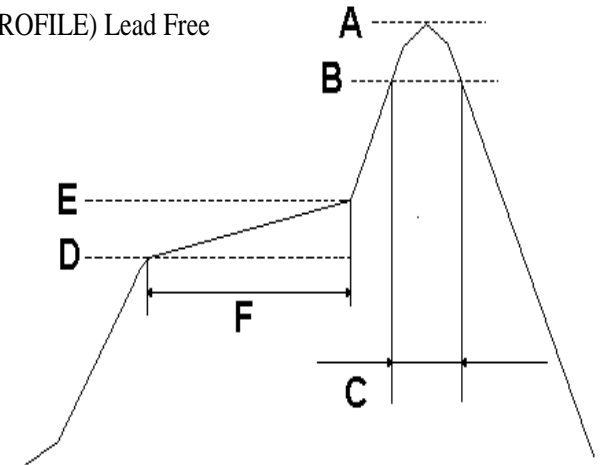
Z vs. FREQUENCY
Impedance Under DC Bias



Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

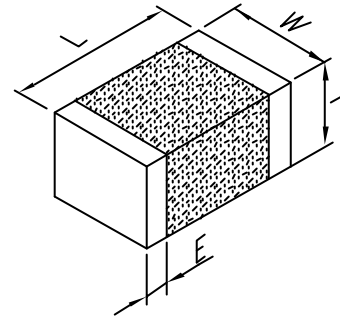
A	260 ± 5
B	230 ± 5
C	30 ± 10sec
D	150
E	180
F	90 ± 30sec



BCCB-3216E1-301T

ELECTRICAL CHARACTERISTICS:

	Z @ 100MHz (Ohms)	DCR (Ohms)	Rated Current
Nominal	300		
Minimum	225		
Maximum	375	0.2	500mA



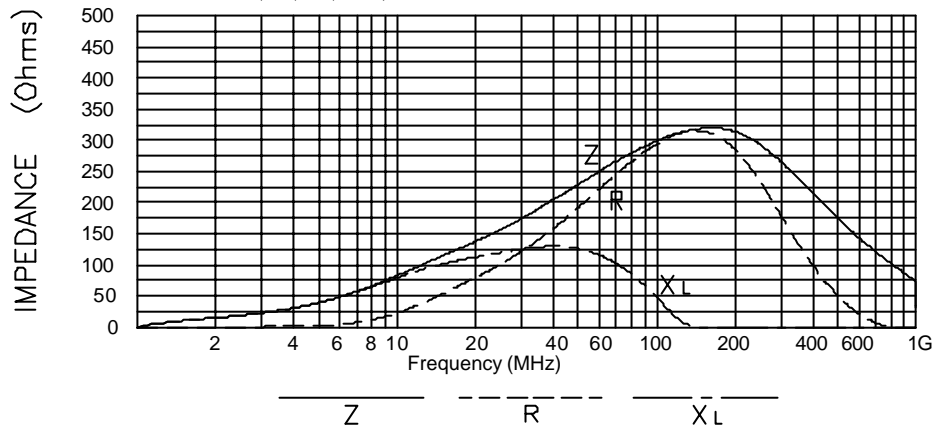
PHYSICAL DIMENSIONS:

L	3.20(0.125) ±0.200(0.008)
W	1.60(0.063) ±0.200(0.008)
T	1.10(0.043) ±0.200(0.008)
E	0.50(0.020) ±0.300(0.012)

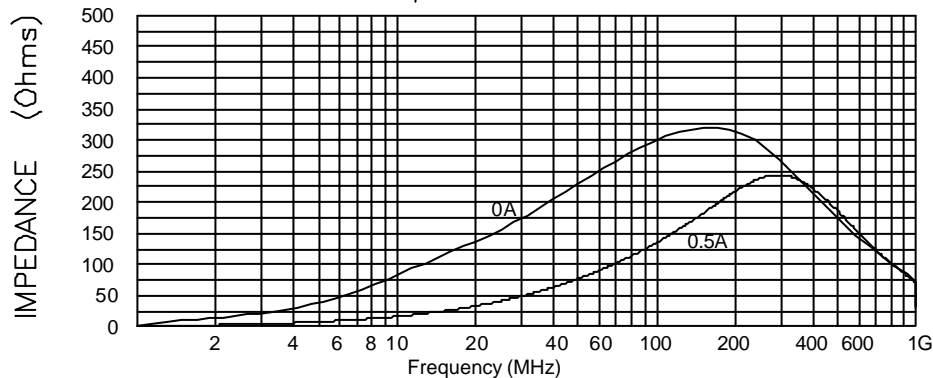
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

|Z| , R, AND X_L vs. FREQUENCY



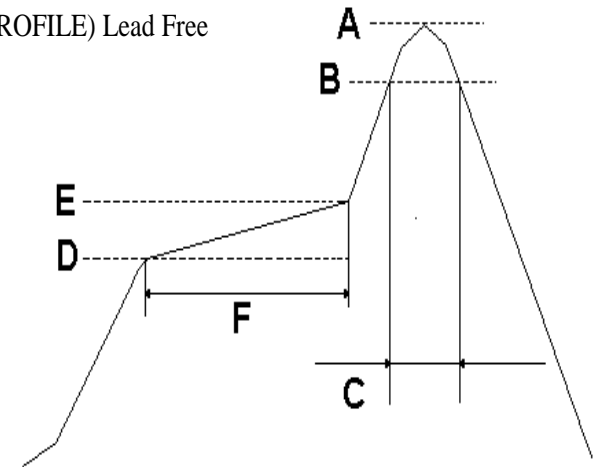
Z vs. FREQUENCY
Impedance Under DC Bias



Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

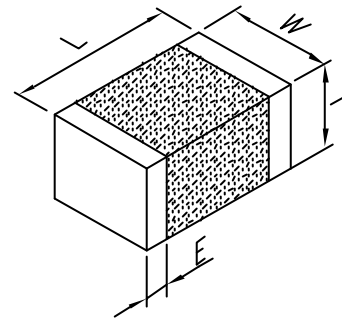
A	260 ± 5
B	230 ± 5
C	30 ± 10sec
D	150
E	180
F	90 ± 30sec



BCCB-3216E1-601T

ELECTRICAL CHARACTERISTICS:

	Z @ 100MHz (Ohms)	DCR (Ohms)	Rated Current
Nominal	600		
Minimum	450		
Maximum	750	0.3	500mA



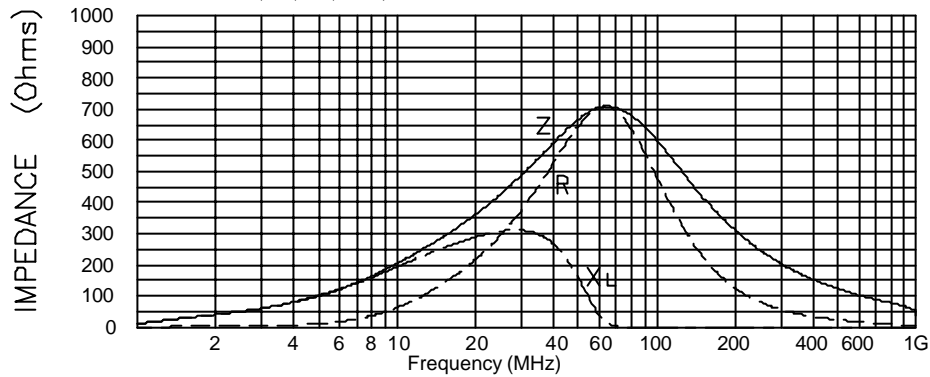
PHYSICAL DIMENSIONS:

- L 3.20(0.126) ±0.200(0.008)
- W 1.60(0.063) ±0.200(0.008)
- T 1.10(0.043) ±0.200(0.008)
- E 0.50(0.020) ±0.300(0.012)

NOTES: UNLESS OTHERWISE SPECIFIED

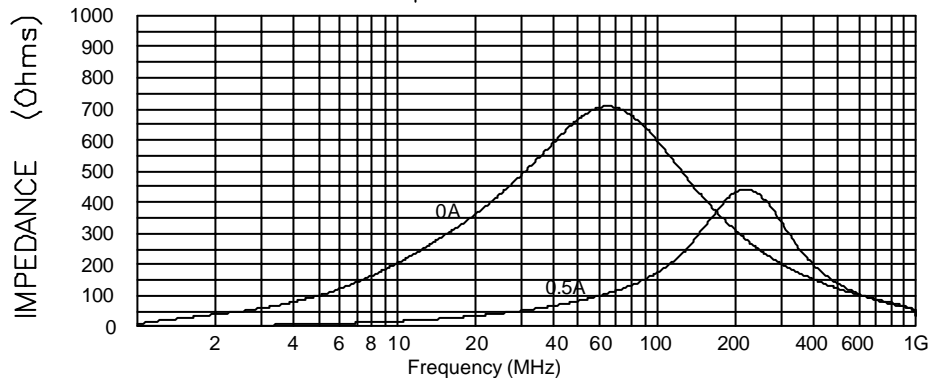
- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

|Z| , R, AND X_L vs. FREQUENCY



— Z ——— R ——— X_L ———

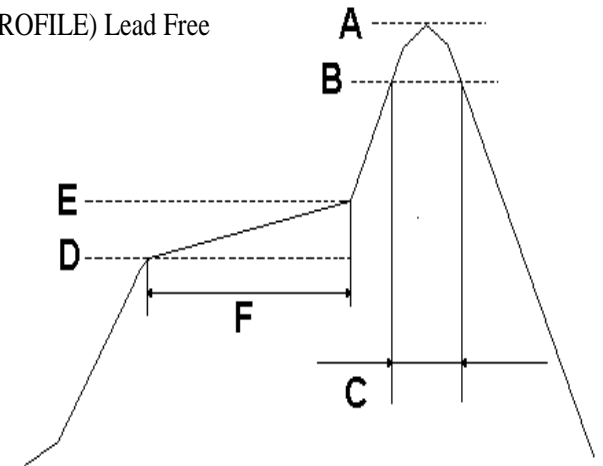
Z vs. FREQUENCY
Impedance Under DC Bias



Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

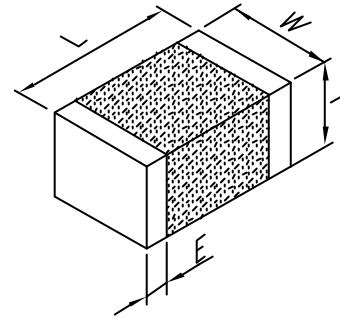
A	260 ± 5
B	230 ± 5
C	30 ± 10sec
D	150
E	180
F	90 ± 30sec



BCCB-3216E1-102T

ELECTRICAL CHARACTERISTICS:

	Z @ 100MHz (Ohms)	DCR (Ohms)	Rated Current
Nominal	1000		
Minimum	750		
Maximum	1250	0.4	200mA



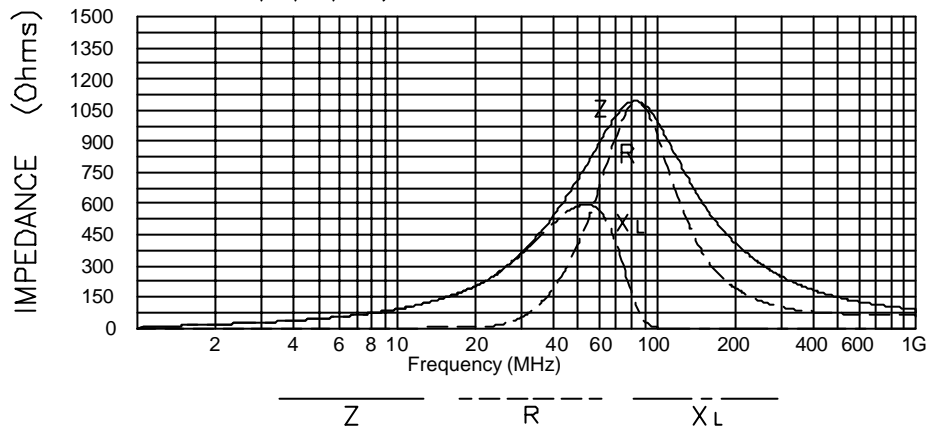
PHYSICAL DIMENSIONS:

- L 3.20(0.126) ±0.200(0.008)
- W 1.60(0.063) ±0.200(0.008)
- T 1.10(0.043) ±0.200(0.008)
- E 0.50(0.020) ±0.300(0.012)

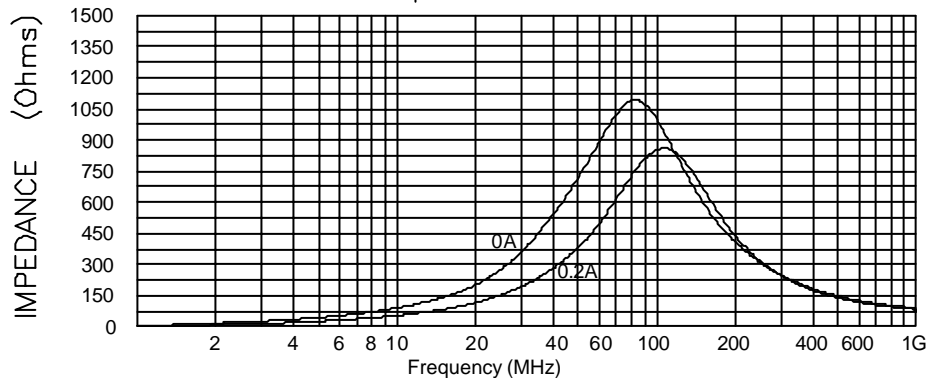
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

|Z| , R, AND X_L vs. FREQUENCY



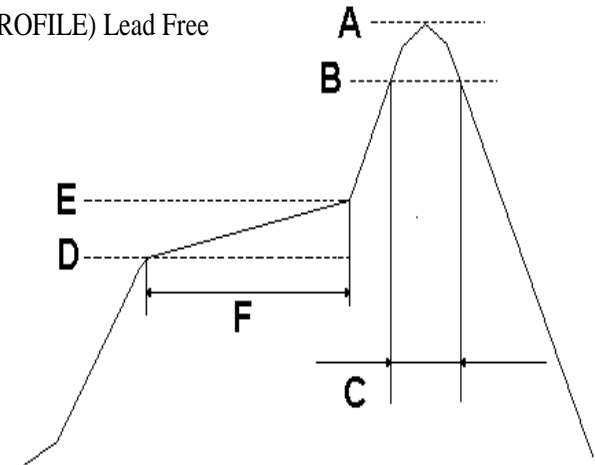
Z vs. FREQUENCY
Impedance Under DC Bias



Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

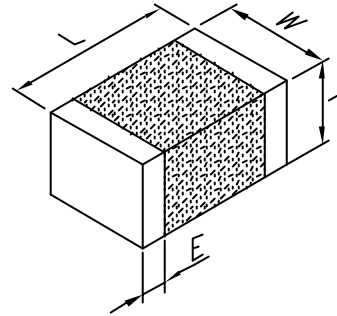
A	260 ± 5
B	230 ± 5
C	30 ± 10sec
D	150
E	180
F	90 ± 30sec



BCCB-3216E1-122T

ELECTRICAL CHARACTERISTICS:

	Z @ 100MHz (Ohms)	DCR (Ohms)	Rated Current
Nominal	1200		
Minimum	900		
Maximum	1500	0.4	200mA



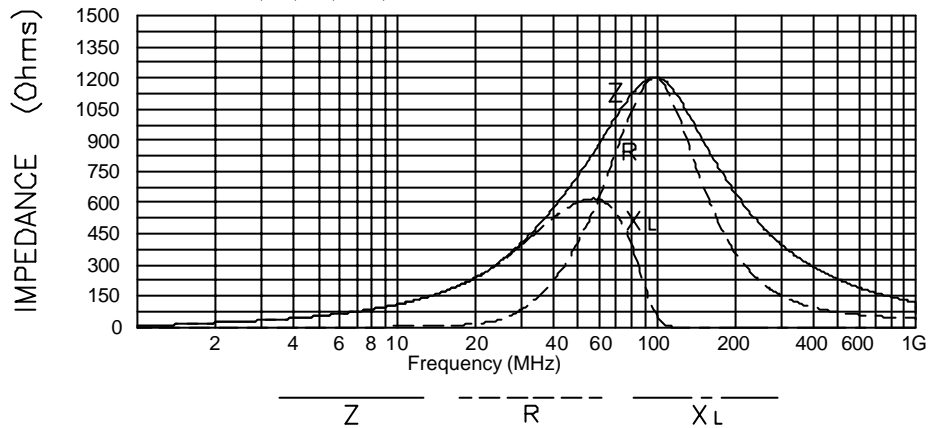
PHYSICAL DIMENSIONS:

L	3.20(0.126) ±0.200(0.008)
W	1.60(0.063) ±0.200(0.008)
T	1.10(0.043) ±0.200(0.008)
E	0.50(0.020) ±0.300(0.012)

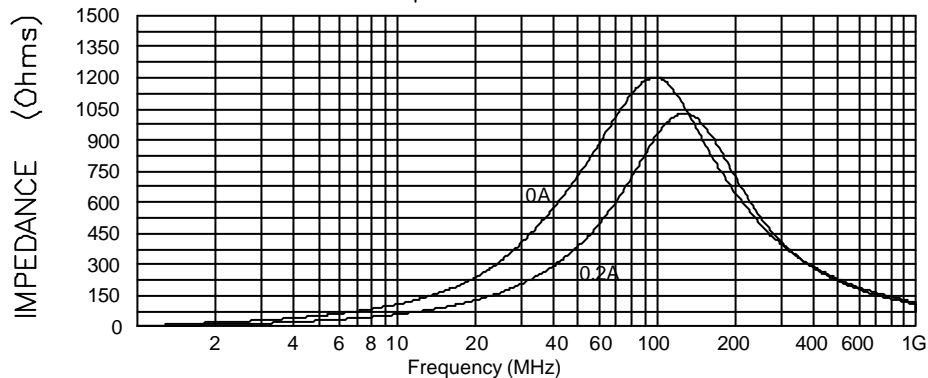
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

|Z| , R, AND X_L vs. FREQUENCY



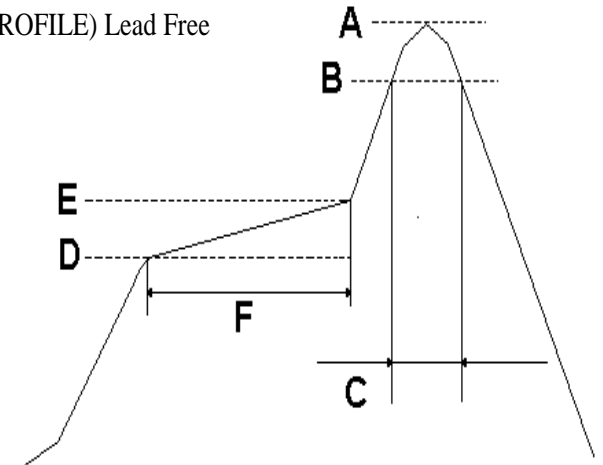
Z vs. FREQUENCY
Impedance Under DC Bias



Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

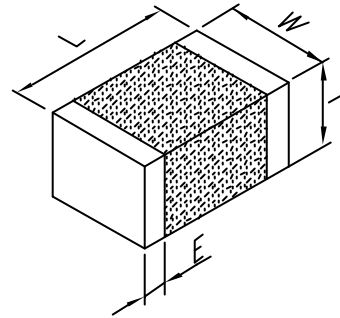
A	260 ± 5
B	230 ± 5
C	30 ± 10sec
D	150
E	180
F	90 ± 30sec



BCCB-3216E1-152T

ELECTRICAL CHARACTERISTICS:

	Z @ 50MHz (Ohms)	DCR (Ohms)	Rated Current
Nominal	1500		
Minimum	1125		
Maximum	1875	0.5	200mA



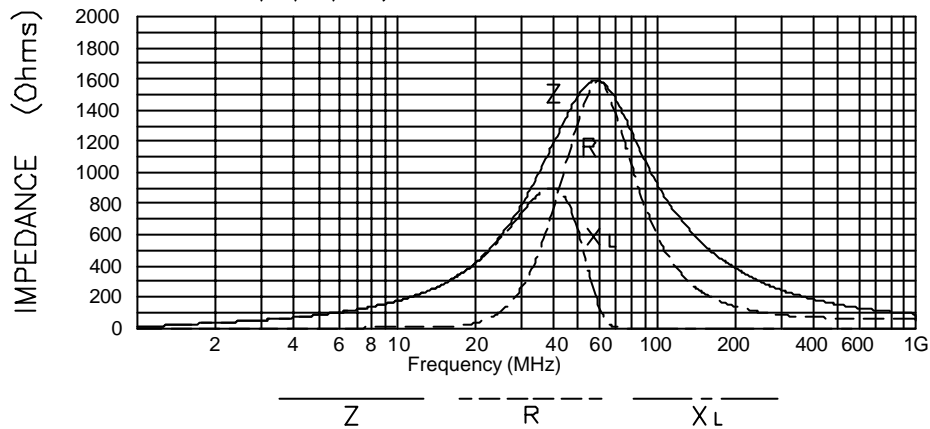
PHYSICAL DIMENSIONS:

L	3.20(0.126) ±0.200(0.008)
W	1.60(0.063) ±0.200(0.008)
T	1.10(0.043) ±0.200(0.008)
E	0.50(0.020) ±0.300(0.012)

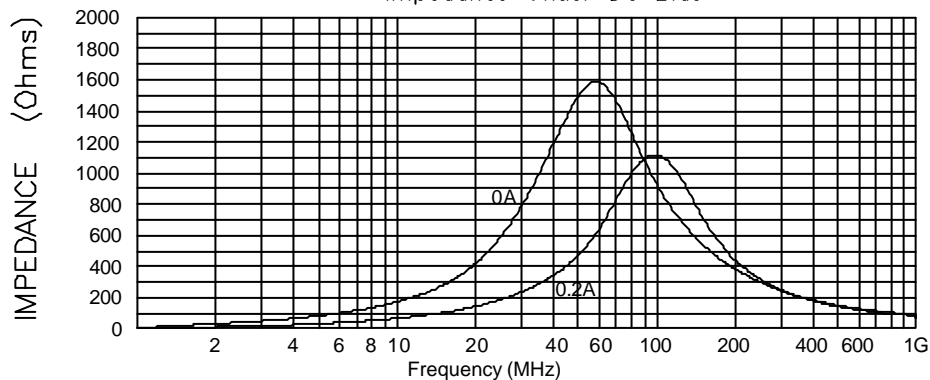
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

|Z| , R, AND X_L vs. FREQUENCY



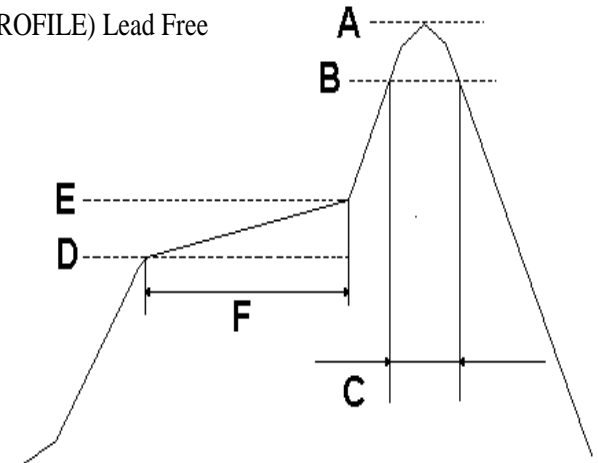
Z vs. FREQUENCY
Impedance Under DC Bias



Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

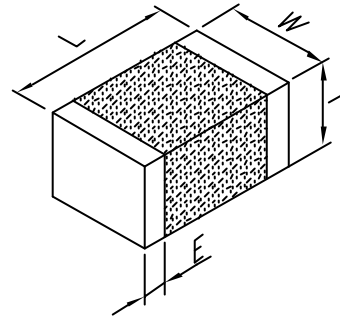
A	260 ± 5
B	230 ± 5
C	30 ± 10sec
D	150
E	180
F	90 ± 30sec



BCCB-3216E1-202T

ELECTRICAL CHARACTERISTICS:

	Z @ 30MHz (Ohms)	DCR (Ohms)	Rated Current
Nominal	2000		
Minimum	1500		
Maximum	2500	0.5	200mA



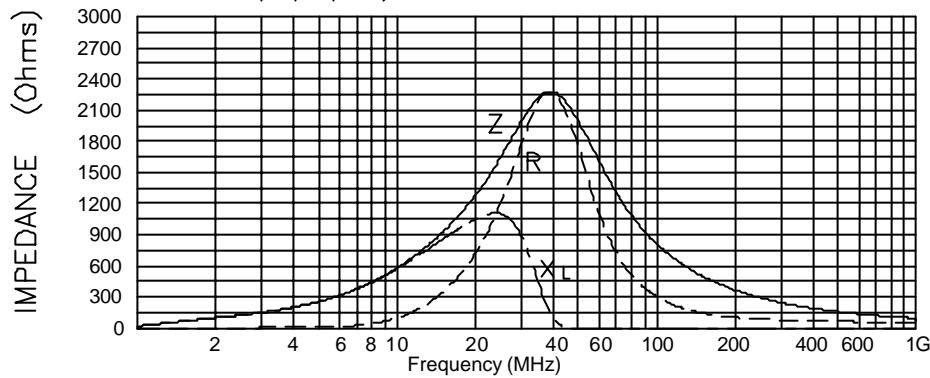
PHYSICAL DIMENSIONS:

- L 3.20(0.126) ±0.200(0.008)
- W 1.60(0.063) ±0.200(0.008)
- T 1.10(0.043) ±0.200(0.008)
- E 0.50(0.020) ±0.300(0.012)

NOTES: UNLESS OTHERWISE SPECIFIED

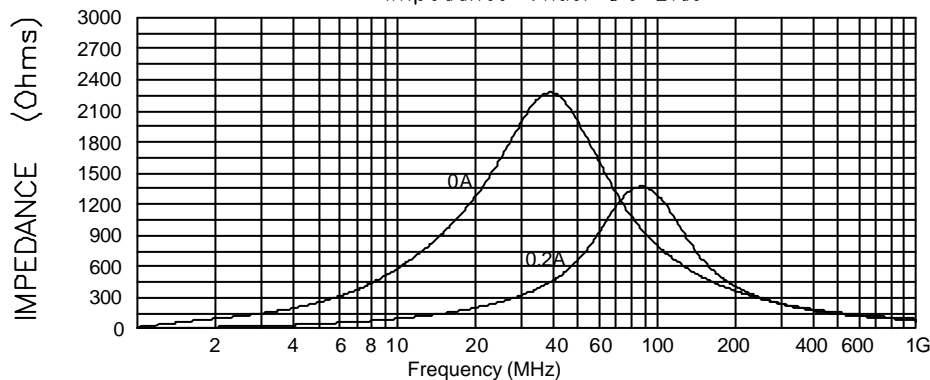
- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

|Z| , R, AND X_L vs. FREQUENCY



----- Z ----- R ----- X_L -----

Z vs. FREQUENCY
Impedance Under DC Bias



Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	260 ± 5
B	230 ± 5
C	30 ± 10sec
D	150
E	180
F	90 ± 30sec

